


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/18/10865	
1.3 Title of PCN	RDL and bumping transfer from the current subco in Taiwan to a new one in Taiwan	
1.4 Product Category	Chipbond in Taiwxan	
1.5 Issue date	2018-04-24	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Richard RENARD
2.1.2 Marketing Manager	Eric PARIS
2.1.3 Quality Manager	Jean-Paul REBRASSE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	ASE subco in China

4. Description of change

	Old	New
4.1 Description	RDL and bumping at subco in Taiwan	RDL and bumping at a new subco in Taiwan (transfer)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no	

5. Reason / motivation for change

5.1 Motivation	The current 6 inches RDL and bumping line will be terminated in December 2018.
5.2 Customer Benefit	MANUFACTURING FLEXIBILITY

6. Marking of parts / traceability of change

6.1 Description	internal codification, new marking and QA number
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7. Timing / schedule

7.1 Date of qualification results	2018-04-24
7.2 Intended start of delivery	2018-08-13
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

10865 Public product.pdf
10865 PCN qualif EMIF06-HSD03F3_ Taiwan.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	EMIF06-HSD03F3	



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : RDL and bumping transfer from the current subco in Taiwan to a new one in Taiwan

PCN Reference : ADG/18/10865

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

EMIF06-HSD03F3		
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